

Solar Cell Cooling and Heat Recovery in a Concentrated Photovoltaic System

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Outline

- The REET research unit
- CPVT systems
- Heat exchanger: prototype and geometry details
- Model implementation
- Results
- Conclusions

The REET Unit at FBK

REET: Renewable Energies and Environmental Technologies

Topics:

- Solar energy
- Non-ionizing radiations
- Biomass
- Geothermal energy

+

Applied research
in collaboration with
companies



Methods:

- Experimental activity
- Numerical simulations
- Partner collaborations

CPV systems

PV: photovoltaics

CPV: concentrated PV

CPV possible *advantages*:

- substitute part of the cell area with inexpensive optics → save money to lower system costs or to use more efficient cells
- increase system efficiency with two axis tracking

CPV possible *disadvantages*:

- more complex system, due to tracking and optics
- no diffused radiation capturing
- optical losses
- thermal issues

Thermal “issues”?

Thermal issues could be transformed in thermal energy gain!

CPVT: CPV + thermal energy recovery

Heat recovery is being widely considered for flat plates (PVT). In CPV systems, heat recovery can solve the problem of cooling.

But...

A compromise is needed for the operating temperature:
as low as possible for cells, as high as possible for heating purposes.

Crucial point: identification of a suitable heating application.

CPVT components

Tracking system: electric motor (e.g., step motor) and gears.

Optics: primary optics (e.g., Fresnel lenses) and secondary optics (e.g., prism).

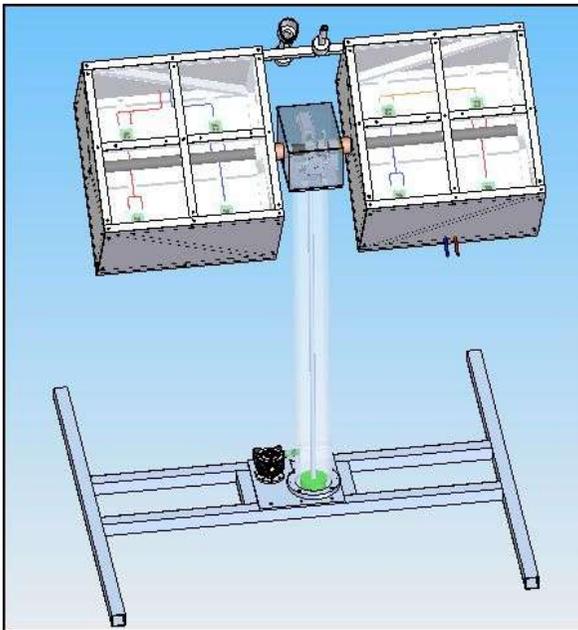
Cells and packaging: PV cells (e.g., triple junction cells) and substrate (e.g., insulated metal substrate).

Heat exchange: exchanger (e.g., micro-channel heat exchanger) and thermal circuit.

Data acquisition and control: sensors (e.g., radiation and temperature sensors), hardware (e.g., PLC), software (tracking algorithm, MMPT algorithm, thermal management algorithm).

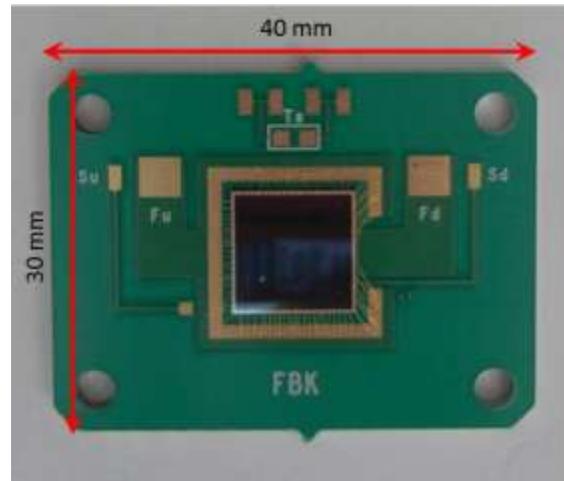
A CPVT prototype

Tracking system and optics
(Bologna University)



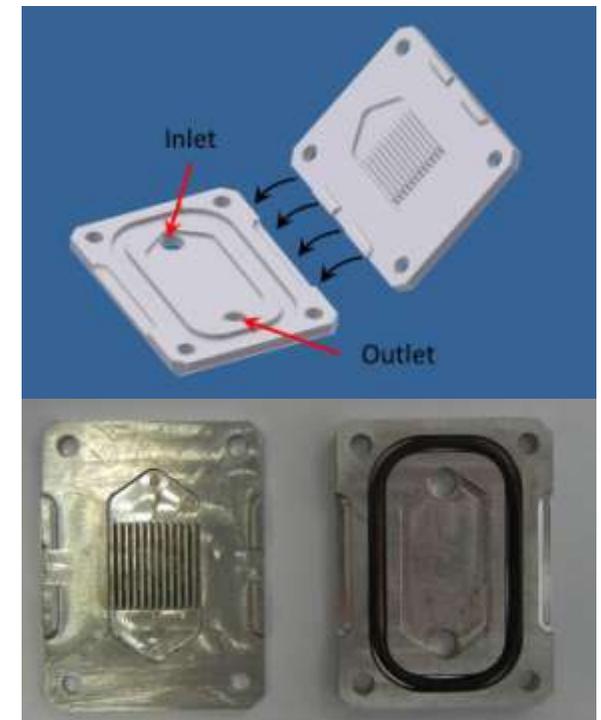
Fresnel lenses, 30 cm x 30 cm

Solar cell and packaging (FBK)



Mono-crystalline Si cells, 1 cm x 1 cm, optimized for 160 suns ($\eta \sim 20\%$)

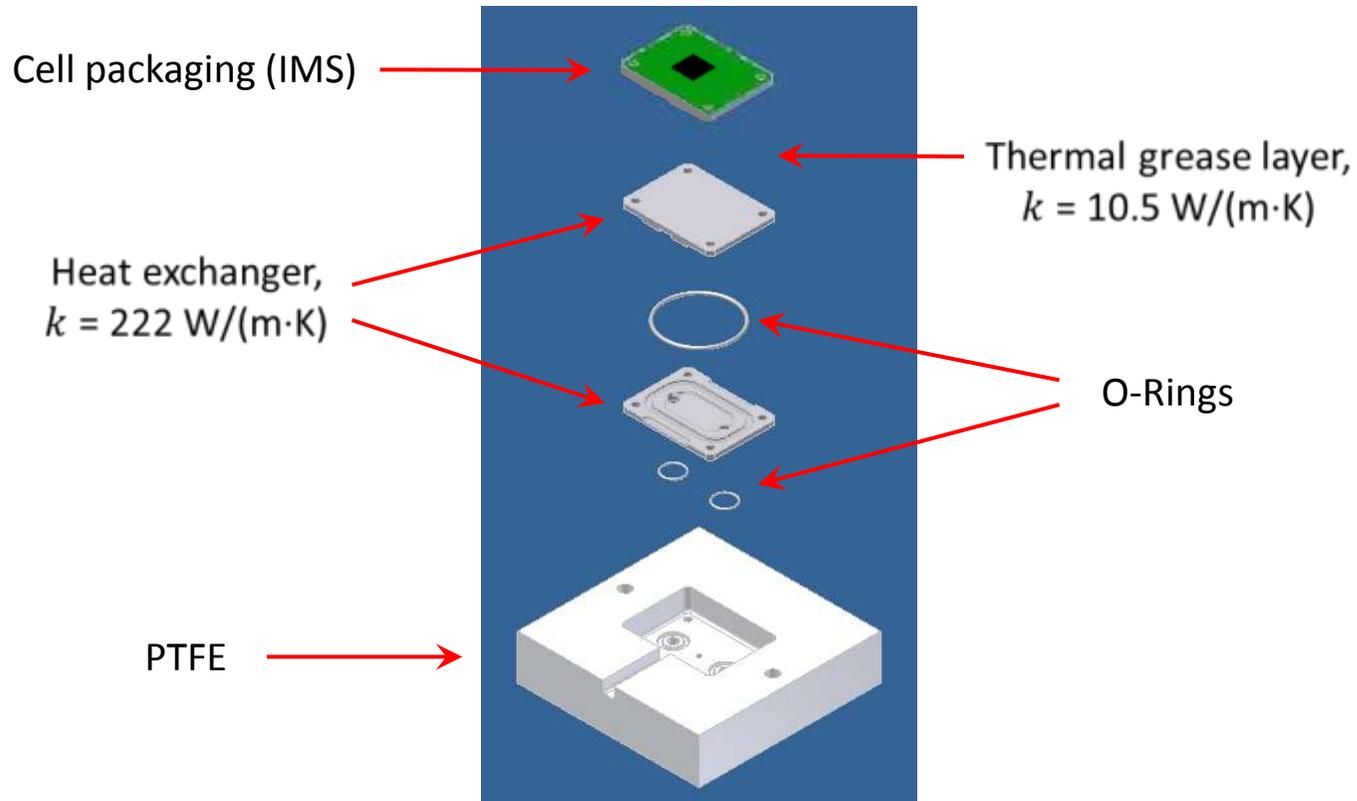
Micro-channel heat exchanger (FBK)



Array of rectangular micro-channels, milled in aluminum

Heat exchange kit

Heat exchanger mounting



Comsol model implementation

Navier-Stokes equations, incompressible fluid (water).

Heat transfer in solids and fluids.

Solver. PARDISO, highly non-linear problem.

Mesh, element order. Unstructured tetrahedral mesh elements (overall heat exchanger), mapped+swept mesh elements (single channel), linear.

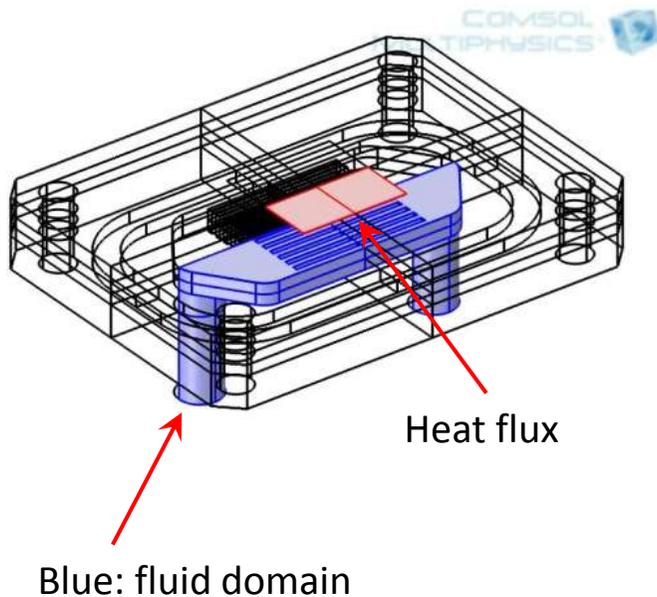
Boundary conditions.

Fluid-dynamics. Walls: no slip b.c.'s. Inlet and outlet: velocity-pressure.

Heat transfer. Insulation, temperature, heat flux, thin insulating layer.

Heat exchanger

Symmetry → reduced geometry



Heat flux: 12.8 W/cm^2 (160 suns = 16 W/cm^2 , minus 20 % electric efficiency)

Inlet temperature: $40 \text{ }^\circ\text{C}$

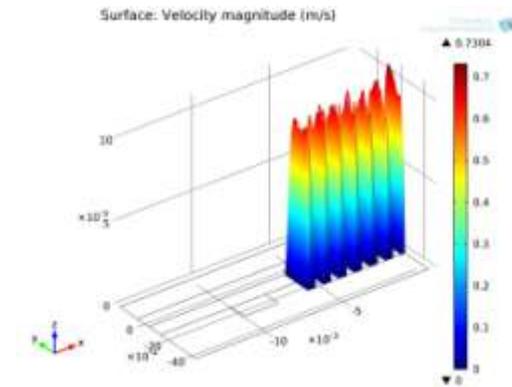
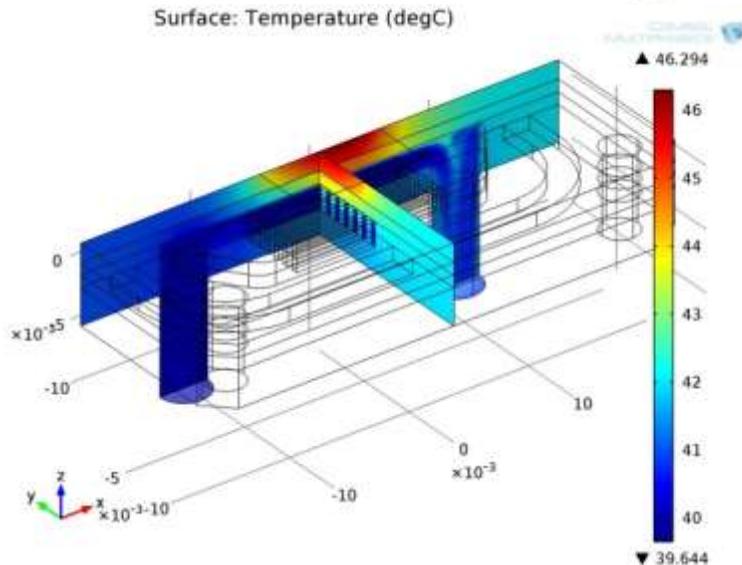
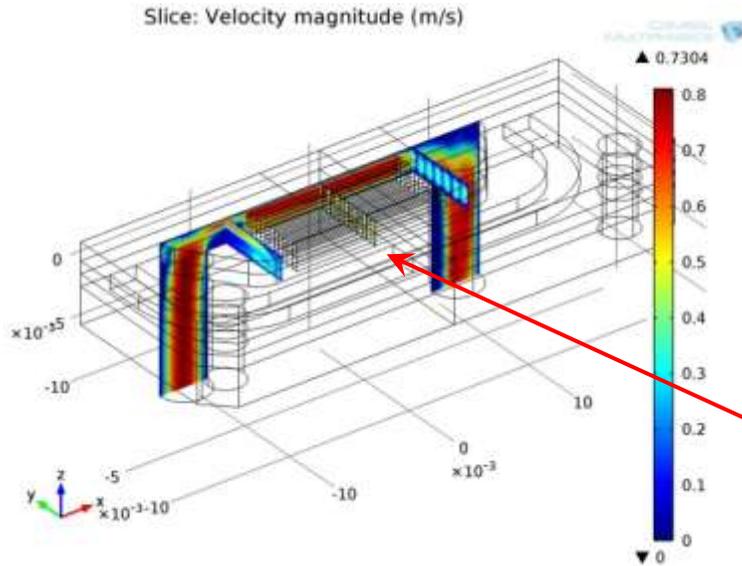
Flow rate: 5 ml/s (water), distributed in 13 channels

Channel cross section: 0.5 mm x 2 mm ($D_h = 800 \text{ } \mu\text{m}$)

Thermal grease layer: $100 \text{ } \mu\text{m}$

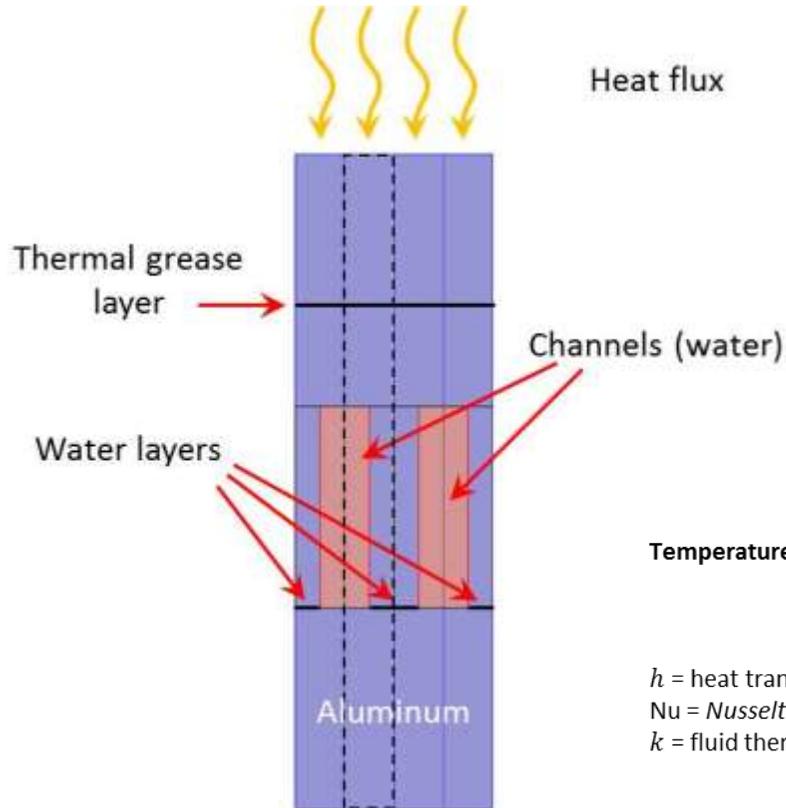
Heat exchanger results

- Balanced flow rate within the channels
- About 6 K of difference between fluid inlet and maximum aluminum temperature ($\Delta T_{HE} = 4$ K, $\Delta T_{IMS-AI} = 2$ K)
- $\Delta p \sim 6.6$ mbar



Velocity distribution within the channels

Single channel geometry



Geometry: array of parallel channels with rectangular cross section
 Large number of channels
 → far from array border solution resembles an *infinite* array
 → **symmetry**

Heat flux q_{rad}
 → completely absorbed by the fluid (water) flowing in the channels
 → *spread* on the channel walls (possibly excluding bottom ones)
 Surface ratio

$$r_{surf} = d_{ch} / (w_{ch} + 2h_{ch}) = 0.22$$

Compare with *straight circular channel* with $D = D_{h,ch}$ and constant radial heat flux $q_{ch} = 0.22 q_{rad}$

Channel *hydraulic diameter*:

$$D_{h,ch} = 4A_{ch} / P_{ch} = 2 w_{ch} h_{ch} / (w_{ch} + h_{ch}) = 0.8 \text{ mm}$$

Temperature difference ΔT_{w-b} between wall and fluid bulk

$$\Delta T_{w-b} = q_{ch} / h$$

h = heat transfer coefficient

Nu = *Nusselt* number

k = fluid thermal conductivity

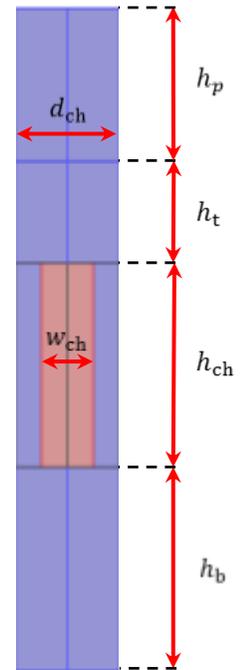
$$h = Nu k / D_{h,ch}$$

Laminar flow: $Nu = 48/11 = 4.36$

Water: $k = 0.6 \text{ W}/(\text{m}\cdot\text{K}) \Rightarrow h = 3273 \text{ W}/(\text{m}^2\cdot\text{K})$

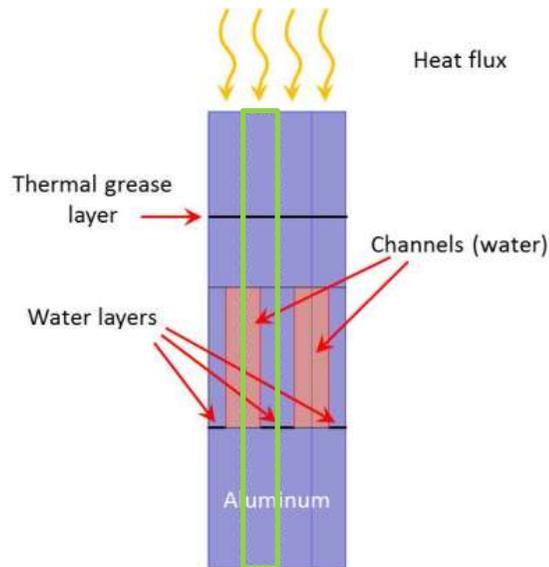
Incident flux $q_{rad} = 12.8 \text{ W}/\text{cm}^2 \Rightarrow q_{ch} = 2.82 \text{ W}/\text{cm}^2$

$$\Rightarrow \Delta T_{w-b} = 8.6 \text{ K}$$

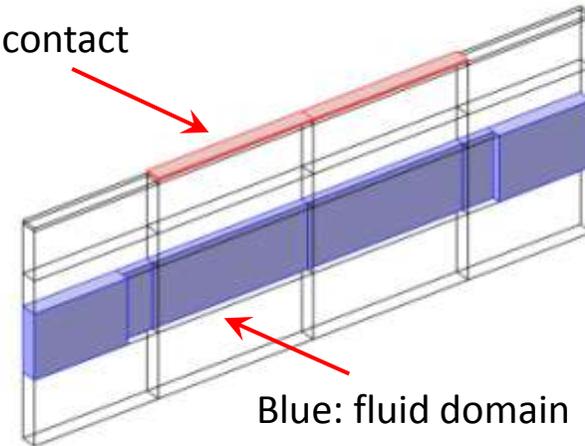


Single channel geometry

Exploit symmetry



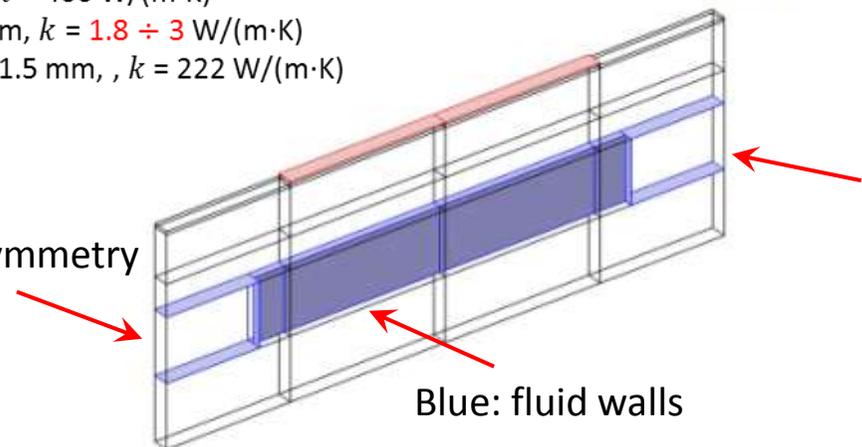
Cell contact



IMS layers:

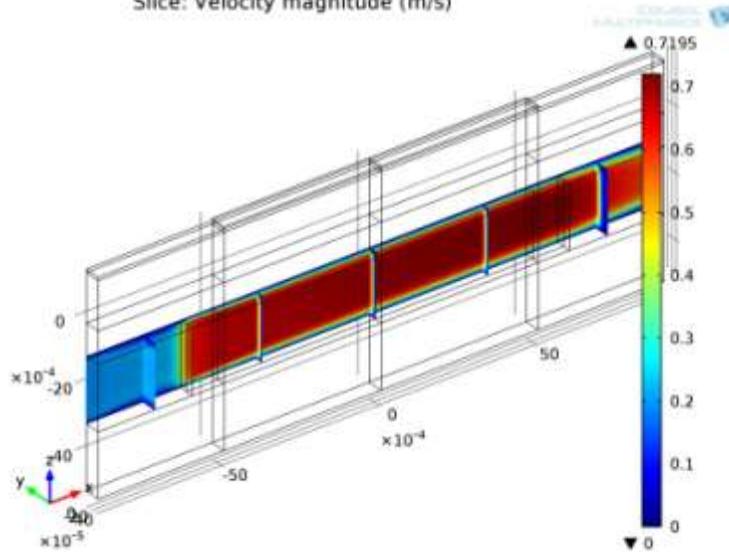
- copper layer, $70 \mu\text{m}$, $k = 400 \text{ W}/(\text{m}\cdot\text{K})$
- dielectric layer, $100 \mu\text{m}$, $k = 1.8 \div 3 \text{ W}/(\text{m}\cdot\text{K})$
- aluminum substrate, 1.5 mm , $k = 222 \text{ W}/(\text{m}\cdot\text{K})$

Lateral symmetry

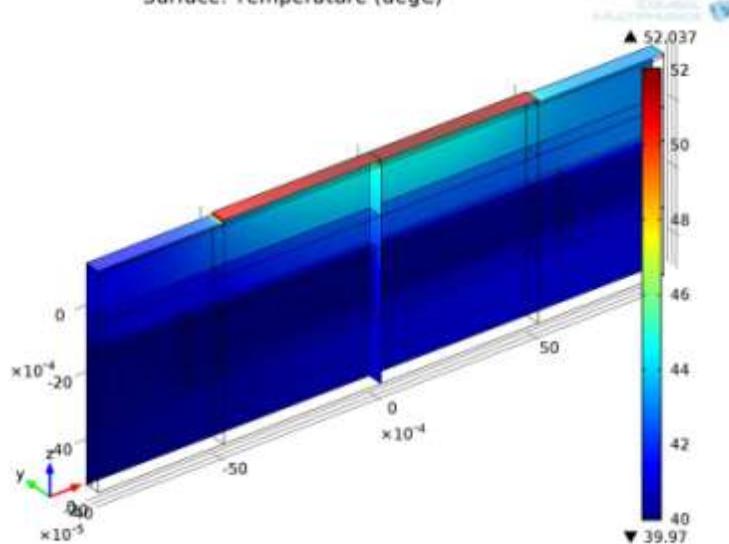


Single channel results

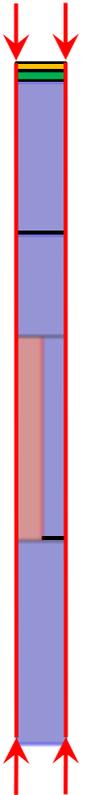
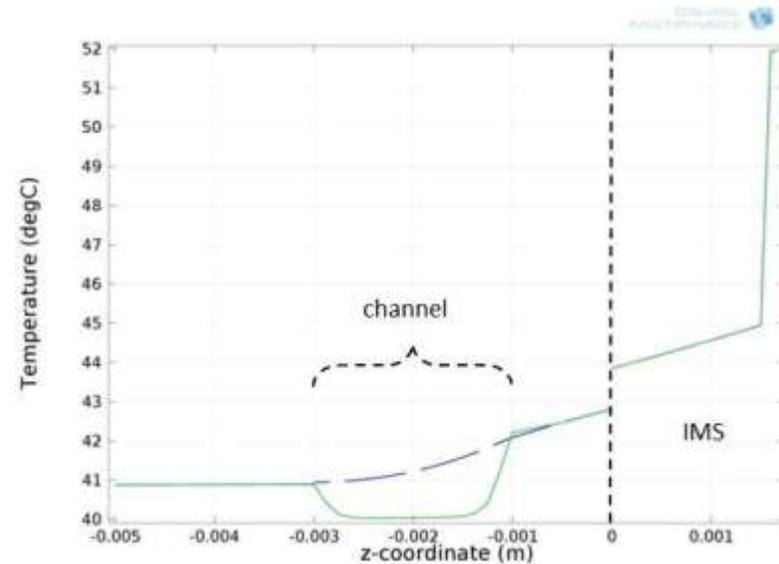
Slice: Velocity magnitude (m/s)



Surface: Temperature (degC)

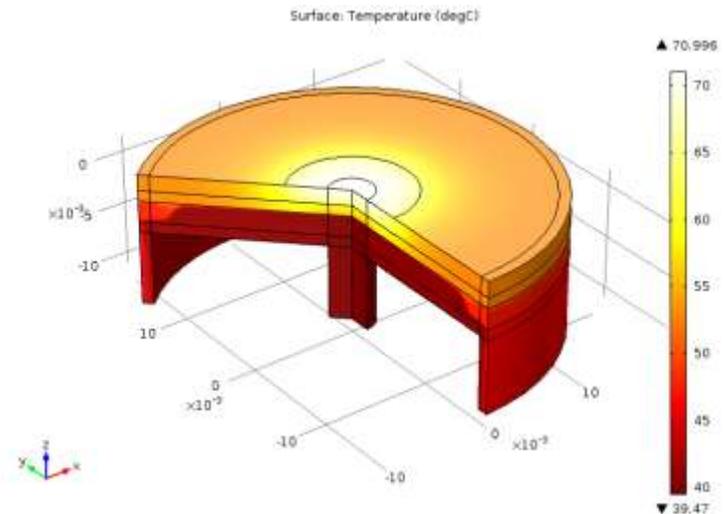
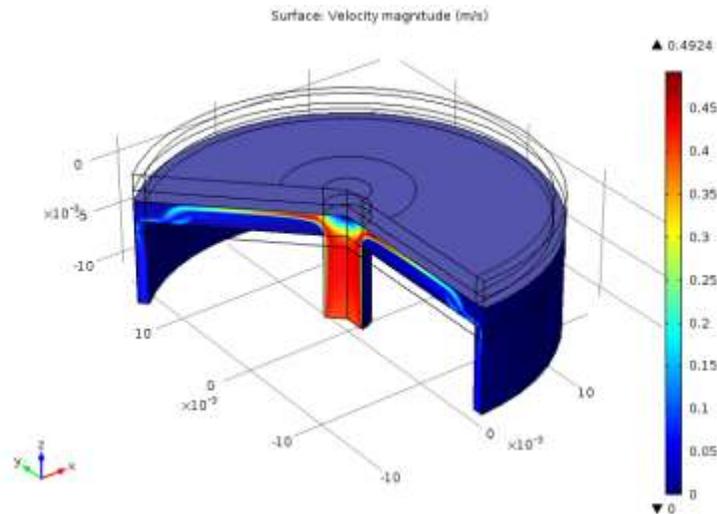


- About 12 K of difference between fluid inlet and maximum cell temperature ($\Delta T_{HE} = 4$ K, $\Delta T_{IMS-Al} = 2$ K, $\Delta T_{IMS-ins} = 6$ K)
- Uniform inflow velocity corresponding to half channel, $\Delta p \sim 4.8$ mbar



Preliminary results

Impinging jets:
promising solution for **triple junction cells**
(1000 suns, $\sim 70 \text{ W/cm}^2$)



Conclusions

- Micro-channel heat exchanger geometry: suitable for Si-cells with IMS packaging (provide manufacturing costs can be lowered)
- Cell packaging: thermal bottleneck given by dielectric layer
- Triple junction cells: improved thermal solutions have to be employed
- Comsol results (in reasonable agreement with analytical estimates) will be validated experimentally

Technical Info

Machine. Processor: double six-core, 2.66 GHz. RAM: 96 GB.

Number of degrees of freedom.

Micro heat exchanger:

- Half-exchanger symmetry: 2,500,000 dof

Single channel:

- Array-like symmetry: about 200,000 dof